

SEMICONDUCTOR PROCESSING TAPE

Abstract

[Problem] To provide a semiconductor processing tape that shows excellent pickup properties and shows low thermal shrinkage rate, no occurrence of wrinkles, no occurrence of displacement in chip position, and sufficient kerf width extension in the tape shrinkage process.

[Means to Solve the Problem] A semiconductor processing tape, which comprises a removable adhesive tape that is provided with a substrate film and a removable adhesive layer formed on at least one side of the substrate film, wherein, in the process of fragmenting the adhesive by expansion, when the tensile elongation of the removable adhesive tape according to the method of JIS7162 is 10%, the relationship between the stress of the substrate alone and the stress of the removable adhesive tape, is:

stress on removable adhesive tape/stress on substrate alone = 1 or less.

Figure 1